



# ORIENT

## Photo coupler

### Product Data Sheet

Name: OR-M501-(HB)

Customer: \_\_\_\_\_

Date: \_\_\_\_\_

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**Preliminary**

This datasheet is a preliminary design specification, and the formal specifications are subject to the recognition letter with jointly signed

### 1. Features

- (1) Compliance Halogens Free (Br < 900ppm, Cl <900ppm, Br+Cl <1500ppm)
- (2) High speed : 1MBd.
- (3) Adapted to the dual-in-line, lead spacing width, surface installation.
- (4) Wide operating temperature range of -40°C to 105°C
- (5) Open collector output.
- (6) Safety approval
  - UL approved(No.E323844)
  - VDE approved(No.40029733)
  - CQC approved (No.CQC19001231256)
- (7) In compliance with RoHS, REACH standards
- (8) MSL Class I



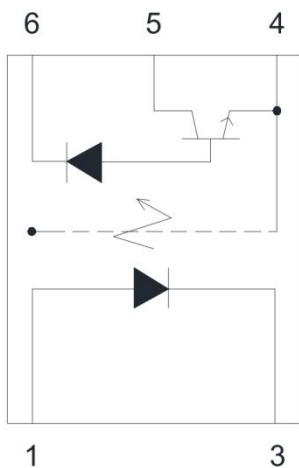
### 2. Instructions

OR-M501-(HB) consists of highly efficient AlGaAs light-emitting diodes and high-speed optical detectors. The design provides good ac and dc isolation at the input and output ends of the photoelectric coupler. Connections related to photodiode biasing can improve the speed of conventional phototransistor couplers by reducing the capacitance of the matrix collector.

### 3. Application Range

- line receiver isolation
- switching power supply
- motor control system

### 4. Functional Diagram



- 1. Anode
- 3. Cathode
- 4. GND
- 5. Vo (Output)
- 6. Vcc

Truth table	
Input ( LED )	Output
ON	L
OFF	H

### 5. Absolute Maximum Ratings (Ta=25°C) \*1

Parameter		Symbol	Rated Value	Unit
Input	Average Forward Input Current	I <sub>F</sub>	20	mA
	Reverse Input Voltage	V <sub>R</sub>	5	V
	Power Dissipation	P <sub>I</sub>	45	mW
Output	Output Collector Current	I <sub>O</sub>	8	mA
	Output Collector Voltage	V <sub>O</sub>	20	V
	Output Collector Power Dissipation	P <sub>O</sub>	100	mW
Supply Voltage		V <sub>CC</sub>	30	V
Insulation Voltage		V <sub>iso</sub>	3750	V <sub>rms</sub>
Operating Temperature		T <sub>opr</sub>	-40~+ 105	°C
Storage Temperature		T <sub>stg</sub>	-55~+ 125	
*2 Soldering Temperature		T <sub>sol</sub>	260	

\*1. Room temperature = 25 °C. Exceeding the maximum absolute rating can permanently damage the device. Working long hours at the maximum absolute rating can affect reliability.

\*2. soldering time is 10 seconds.

### 6. Recommended Operating Conditions

Characteristics	Symbol	Min	Typ.	Max	Unit
Supply voltage	V <sub>CC</sub>	2.7	---	24	V
Forward current	I <sub>F</sub>	7	---	16	mA
Operating temperature	T <sub>opr</sub>	-40	---	105	°C

Note:

Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

## 7. Electrical optical characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Forward voltage	$V_F$	1.2	1.4	1.8	V	$I_F = 16\text{mA}$
Reverse voltage	$BV_R$	5	—	—	V	$I_R = 10\mu\text{A}$
Current transfer ratio	CTR	20	33	50	%	$I_F = 16\text{mA}, V_O = 0.4\text{V}, V_{CC} = 4.5\text{V}$
Low Level Output Voltage	$V_{OL}$	—	0.2	0.5	V	$V_{CC} = 4.5\text{V}, I_F = 16\text{mA}, I_O = 2.4\text{mA}$
		—	0.2	0.4	V	$V_{CC} = 4.5\text{V}, I_F = 16\text{mA}, I_O = 3.0\text{mA}$
High Level Output Current	$I_{OH}$	—	0.01	1	$\mu\text{A}$	$V_{CC} = 15\text{V}, V_O = 15\text{V}, I_F = 0\text{mA}$
Low Level Supply Current	$I_{CCL}$	—	220	—	$\mu\text{A}$	$I_F = 16\text{mA}, V_O = \text{open}, V_{CC} = 15\text{V}$
High Level Supply Current	$I_{CCH}$	—	0.002	1	$\mu\text{A}$	$I_F = 0\text{mA}, V_O = \text{open}, V_{CC} = 15\text{V}$

Typical values at  $T_A = 25^\circ\text{C}$

## 8. Switching Characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Propagation delay time to output Low level	$t_{PHL}$	$R_L = 1.9\text{k}\Omega$ $I_F = 16\text{mA}$	—	0.39	0.8	$\mu\text{s}$
Propagation delay time to output High level	$t_{PLH}$	$R_L = 1.9\text{k}\Omega$ $I_F = 16\text{mA}$	—	0.55	0.8	$\mu\text{s}$

Typical values at  $T_A = 25^\circ\text{C}$

## 9. Isolation characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Withstand Insulation Test Voltage	$V_{ISO}$	$RH \leq 50\%$ , $t = 1 \text{ min}$ , $T_A = 25^\circ\text{C}$	3750	—	—	$V_{RMS}$
Input-Output Resistance	$R_{I-O}$	$V_{I-O} = 500\text{V DC}$	—	$10^{12}$	—	$\Omega$

Typical values at  $T_A = 25^\circ\text{C}$



## 10. Order Information

Part Number

**OR-M501-X-Y-Z-(HB)**

Note

X = Tape and reel option (TP or TP1).

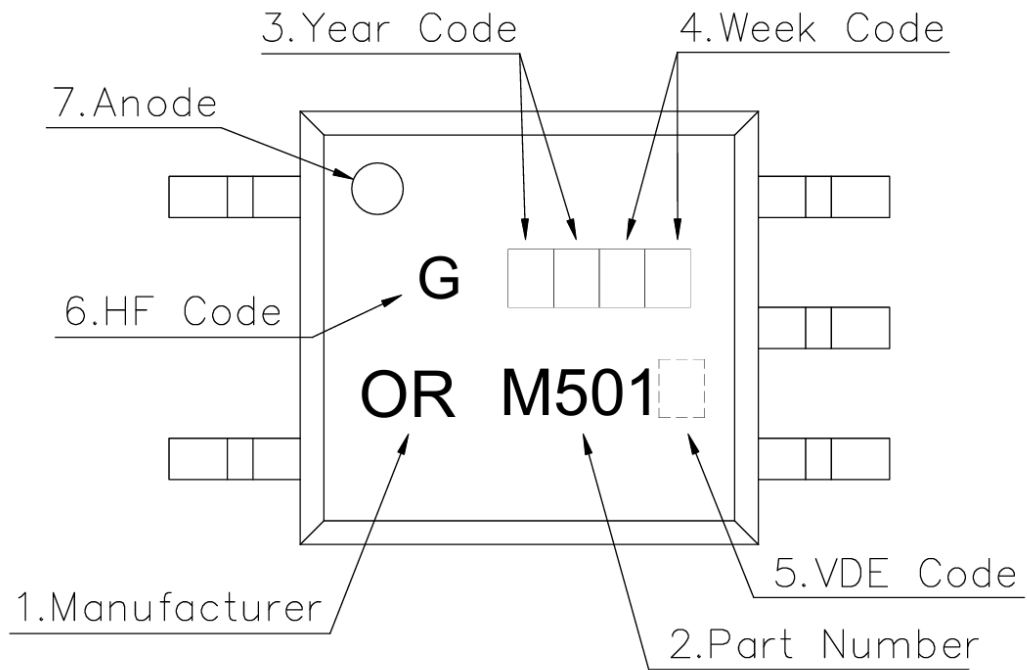
Y = 'V' code for VDE safety (This options is not necessary).

Z = 'G' code for Halogen free.

\* VDE Code can be selected.

Option	Description	Packing quantity
TP	Surface mount lead form (low profile) + TP tape & reel option	3000 units per reel
TP1	Surface mount lead form (low profile) + TP1 tape & reel option	3000 units per reel

## 11. Naming Rule

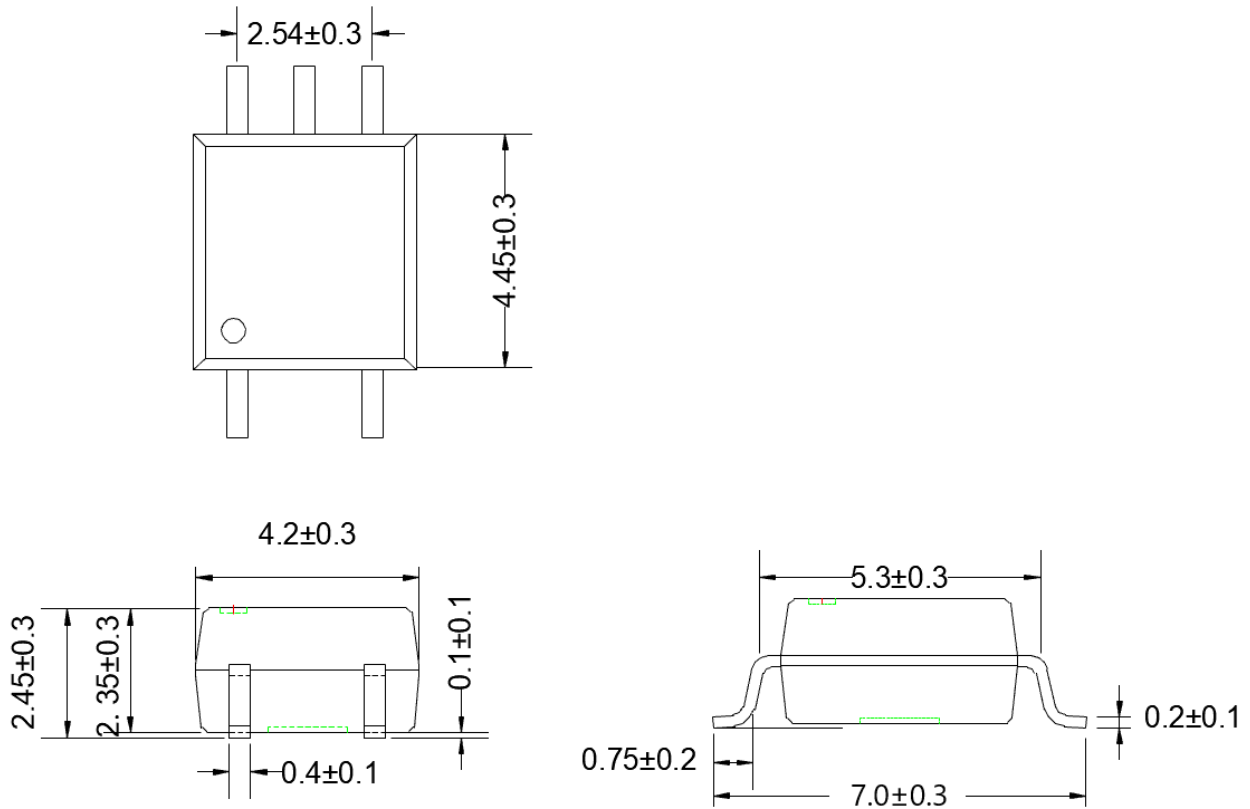


1. Manufacturer : ORIENT.
2. Part Number : M501.
3. Year Code   : '21' means '2021' and so on.
4. Week Code   : 01 means the first week, 02 means the second week and so on.
5. VDE Code  . (Optional)
6. HF Code 'G': Halogen Free.
7. Anode.

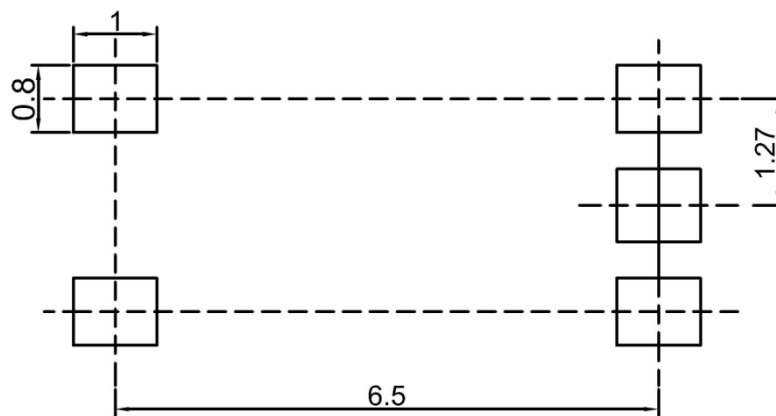
\* VDE Code can be selected.

## 12. Outer Dimension

(1) OR-M501



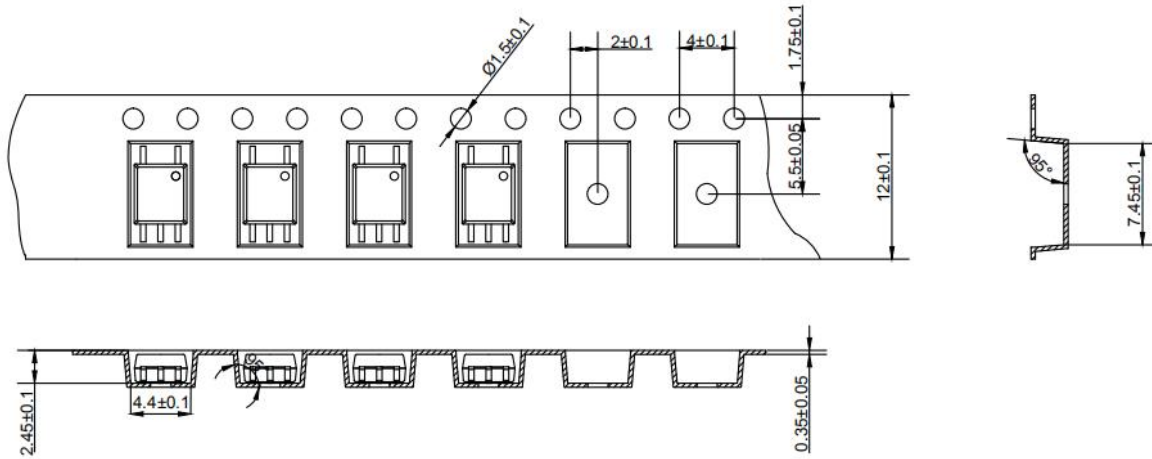
## 13. Recommended Foot Print Patterns (Mount Pad)



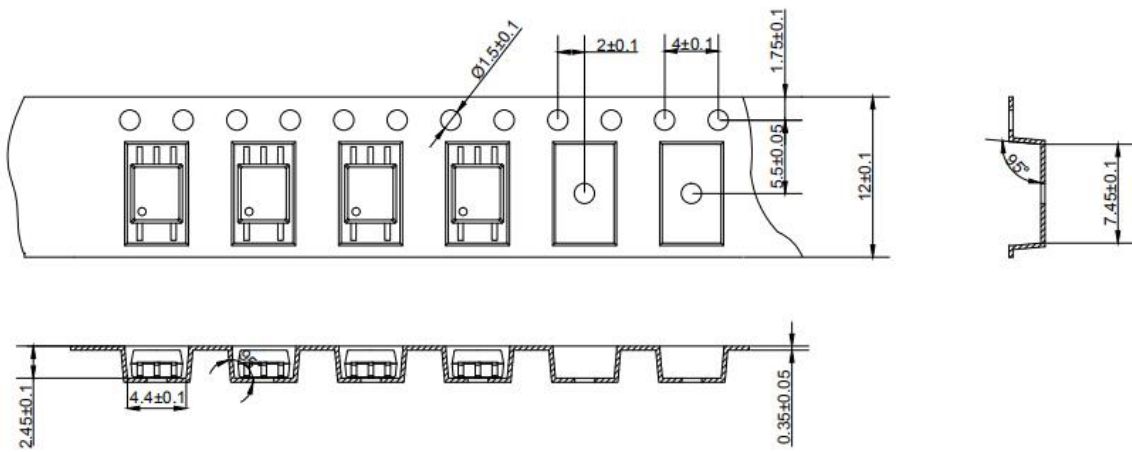
unit : mm

### 14. Taping Dimensions

(1) OR-M501-TP



(2) OR-M501-TP1



Description	Symbol	Dimension in mm(inch)
Tape wide	W	12±0.3 (0.472)
Pitch of sprocket holes	P0	4±0.1 (0.157)
Distance of compartment	F	5.5±0.1 (0.217)
	P2	2±0.1 (0.079)
Distance of compartment to compartment	P1	8±0.1 (0.315)

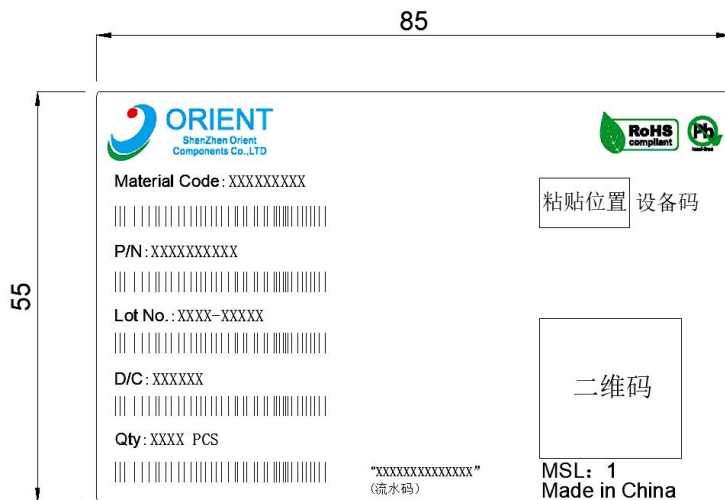
Encapsulation type	TP/TP1
amount (pcs)	3000

## 15. Package Dimension

### (1) package dimension

Packing Information	
Packing type	Reel type
Tape Width	12mm
Qty per Reel	3,000pcs
Small box (inner) Dimension	345*345*45mm
Large box (Outer) Dimension	480x360x360mm
Max qty per small box	6,000pcs
Max qty per large box	60,000pcs

### (2)Packing Label Sample



#### Note:

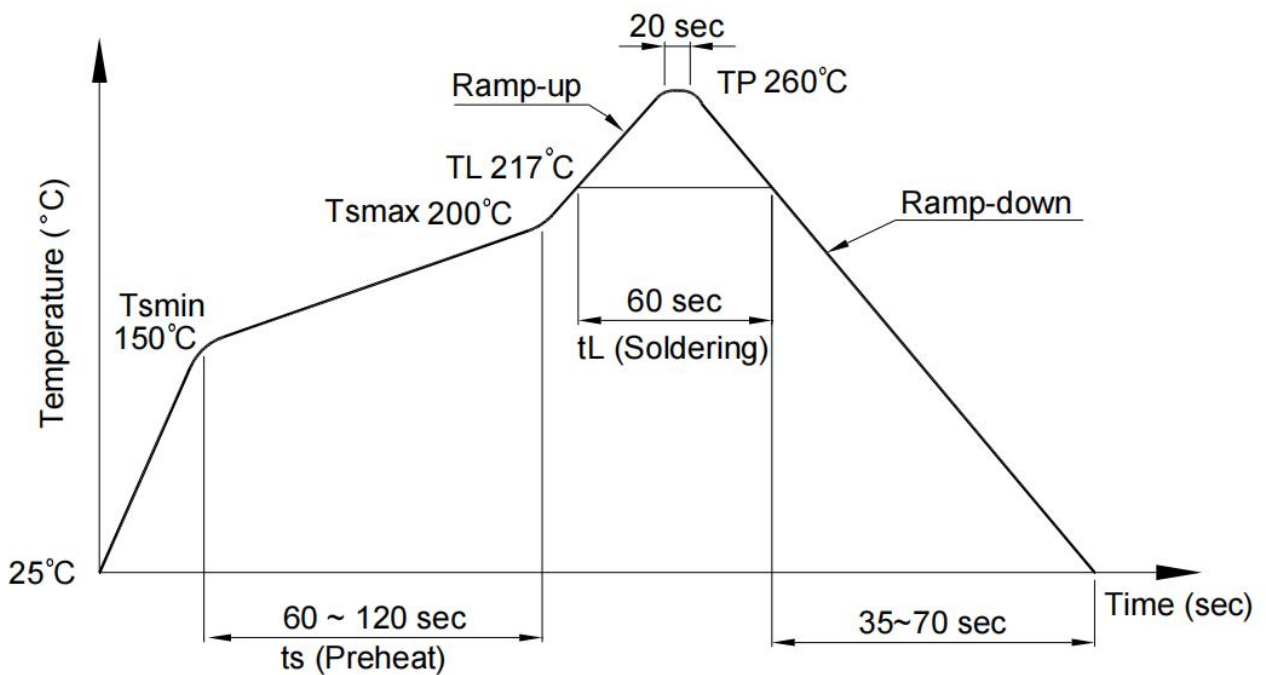
1. Material Code :Product ID.
2. P/N :Contents with "Order Information" in the specification.
3. Lot No. :Product weeks.
4. D/C :Product data.
5. Quantity :Packaging quantity.

## 16. Temperature Profile Of Soldering

(1) IR Reflow soldering (JEDEC-STD-020 compliant)

Note: one solder backflow is recommended under the conditions described below in the temperature and time profile. Do not weld more than three times.

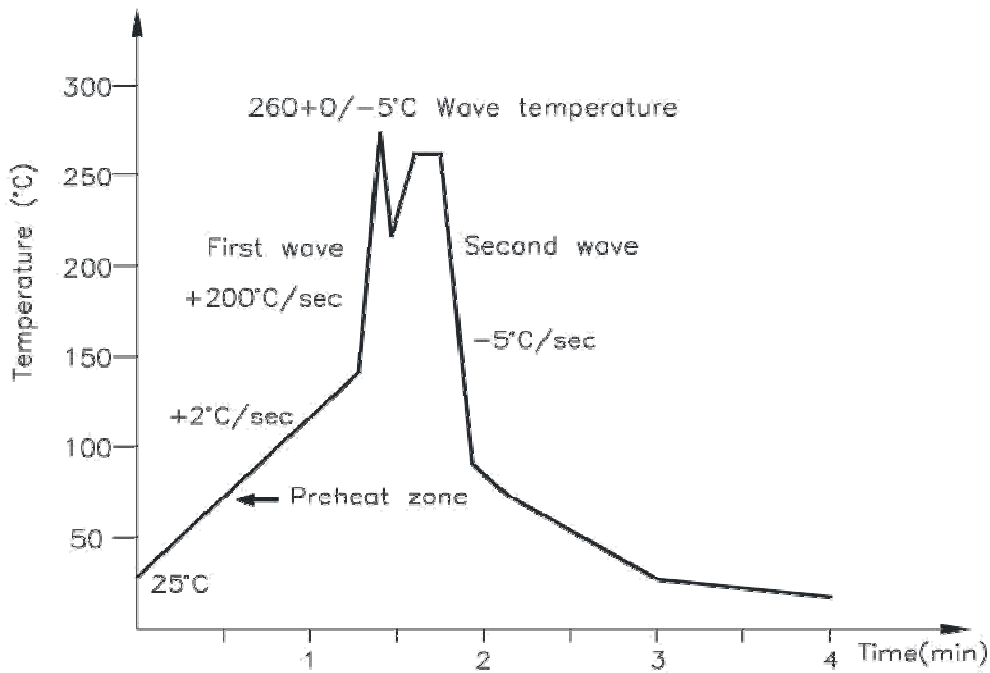
Profile item	Conditions
Preheat - Temperature Min (T Smin ) - Temperature Max (T Smax ) - Time (min to max) (ts)	150°C 200°C 90±30 sec
Soldering zone - Temperature (TL ) - Time (t L )	217°C 60 sec
Peak Temperature	260°C
Peak Temperature time	20 sec
Ramp-up rate	3°C / sec max.
Ramp-down rate from peak temperature	3~6°C / sec
Reflow times	≤3



(2) Wave soldering (JEDEC22A111 compliant)

One-time welding is recommended under the temperature condition.

Temperature	260+0/-5°C
Time	10 sec
Preheat temperature	5 to 140°C
Preheat time	30 to 80 sec



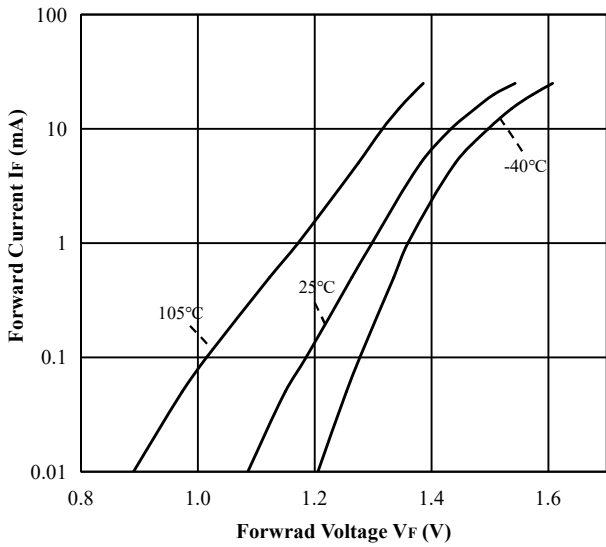
(3) Hand soldering by soldering iron

Single lead welding is allowed in each process and one-time welding is recommended.

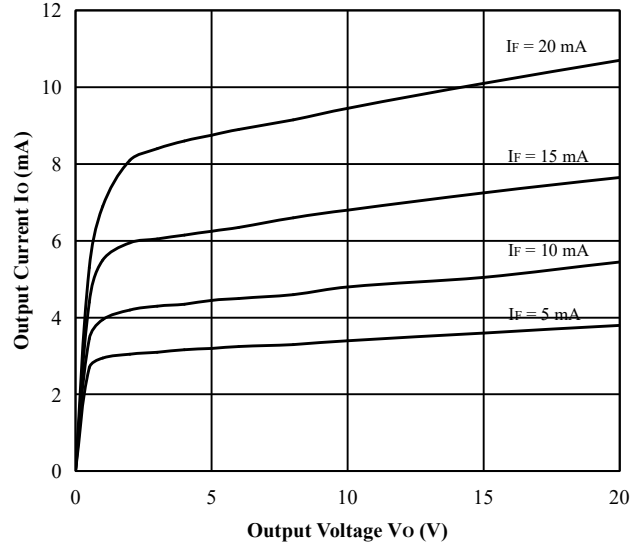
Temperature	380+0/-5°C
Time	3 sec max

### 17. Characteristics Curve

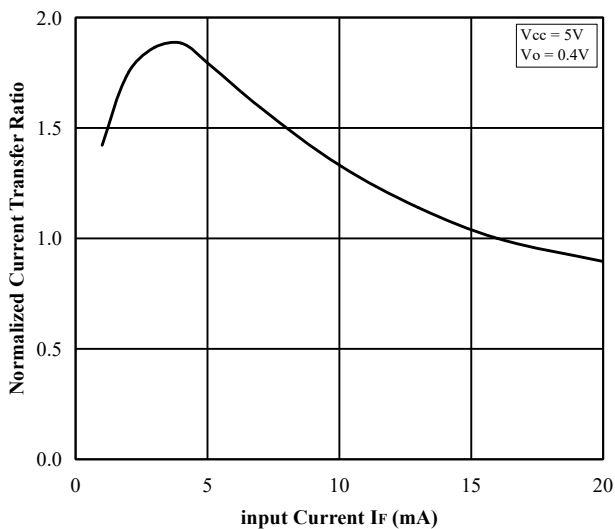
**FORWARD CURRENT vs. FORWARD VOLTAGE**



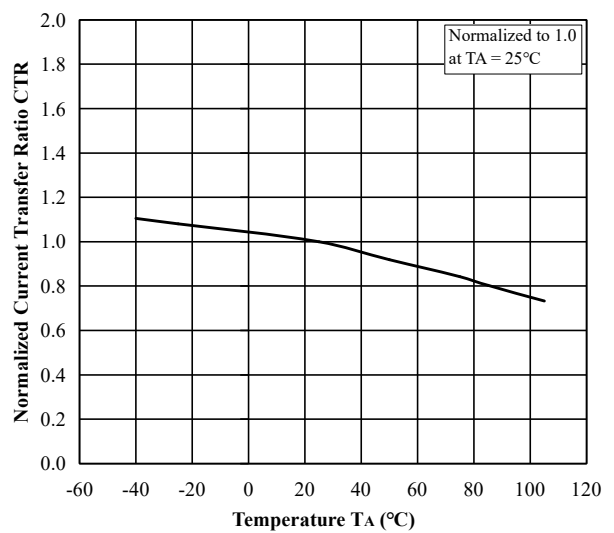
**OUTPUT CURRENT vs. OUTPUT VOLTAGE**



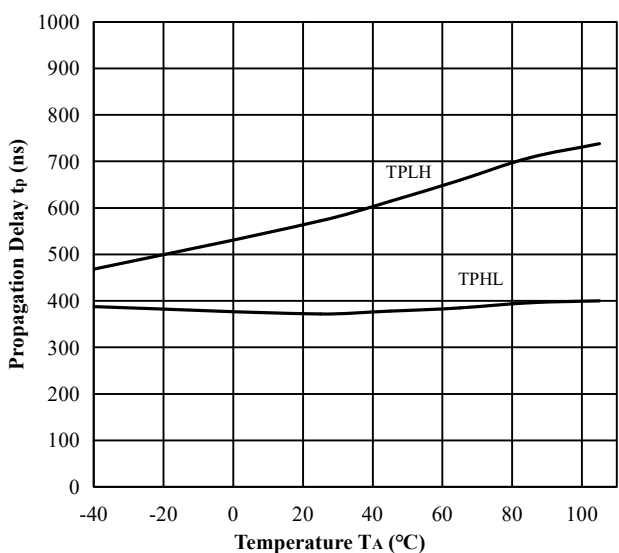
**CURRENT TRANSFER RATIO vs. INPUT CURRENT**



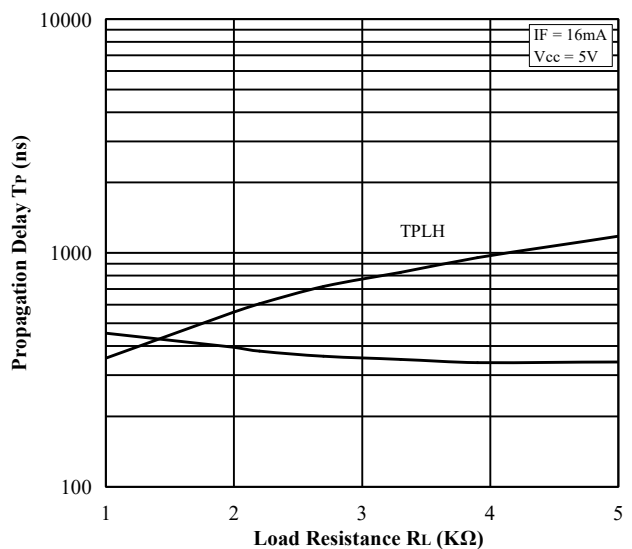
**CURRENT TRANSFER RATIO vs. TEMPERATURE**



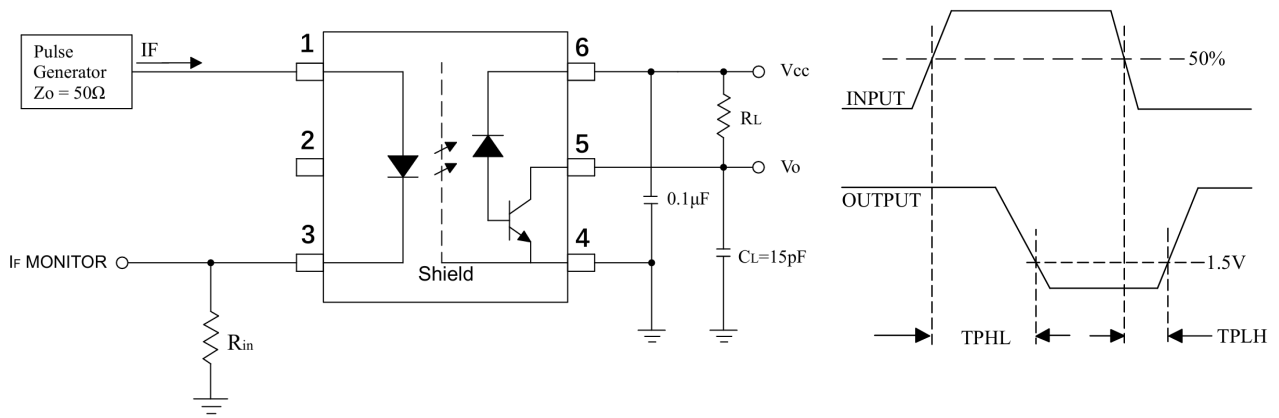
**PROPAGATION DELAY TIME vs. TEMPERATURE**



**PROPAGATION DELAY vs. LOAD RESISTANCE**



### 18. Switching Time Test Circuit



Test Circuit for  $t_{PHL}$  and  $t_{PLH}$



## 19. NOTES

- (1) Orient is continually improving the quality, reliability, function or design and Orient reserves the right to make changes without further notices.
- (2) The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- (3) For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- (4) When requiring a device for any “specific” application, please contact our sales in advice.
- (5) If there are any questions about the contents of this publication, please contact us at your convenience.
- (6) The contents described herein are subject to change without prior notice.
- (7) Immerge unit’s body in solder paste is not recommended.